





COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01040	REV: A	SUN REV: Not In VersionControl
PLOT NAME = Bottom Assembly Drawing			
GENERATED : 5/16/2018 1:10:39 PM		TEXAS INSTRUMENTS	

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